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DRG. NO. B-2499

SH 1 REV. A

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Layer Order

1. Signal_1

2. Power_1 VCC

3. Signal_2

0.062"
+/- .008"

0.034"

4. Signal_3

5. Power_2 GND

6. Signal_4

0.007"

0.005"

149.000±.100

mm

74.000±.100

mm

C

C

Board Characteristics

1. Dimensions are given in inches and mm;
2. Material FR4;
3. Min trace width: 0.006" on all layers;
4. Min. clearance: 0.006" on all layers;
5. 1 oz copper for top, bottom and power layers;
6. Electroless Nickel/Immersion Gold plating. Apply soldermask;
7. FHS tolerances: 0.002";
8. Board thickness and inter-layer spacing as specified;
9. Silkscreen on both sides;
10. Trace impedance: 55 Ohm +/-5 Ohm for 0.006" traces on all layers;

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BOARD'S DRILL SCHEDULE

FHS [Inches]	COUNT	PLATED	COMMENT
.02	362	YES	
.041	100	YES	
.042	80	YES	
.0551	4	NO	
.057	2	YES	
.1063	8	NO	

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QUESTIONS SPECIFIED DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL DIMENSIONS ARE DECIMALS UNLESS OTHERWISE SPECIFIED.

CONTRACT NO.	TITLE
APPROVALS	The University of Chicago Electronics Development Group
DATE	
10/10/02	
DRAM M. Bogdan	
CHECKED H. Sander's	
10/10/02	
ISSUED	
SIZE	FSC# NO.
B	
SCALE	DRG. NO.
	B-2499
	SHEET 1/1

THIS SHEET IS COMPUTER GENERATED

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